



ZT3220E, ZT3221E, ZT3222E, ZT3223E, ZT3232E, ZT1385E

Low Power +3V to +5.5V, 250kbps RS232 Transceivers



Features

- Meets EIA/TIA-232F and CCITT V.28/V.24 specifications for V_{CC} at +3.3V $\pm 10\%$ and +5V $\pm 10\%$
- Low Quiescent Current: 0.5mA typ., 1mA max.
- Low Shutdown Current (where applicable): 1 μ A typical, 10 μ A max.
- Guaranteed Data Rate 250kbps
- Proprietary Switch-Capacitor Regulated Voltage Converters (patent pending)
- Proprietary AUTOGREEN Power Saving (patent pending)
- Latch-up Free
- ESD Protection for RS-232 I/O's
 - ±15kV Human Body Model (HBM)
 - ±15kV EN61000-4-2 Air Gap Discharge
 - ±8kV EN61000-4-2 Contact Discharge
- Drop-in Replacements for MAX3220E, SP3220E, MAX3221E, ICL3221E, MAX3222E, ICL3222E, SP3222E, MAX3223E, ICL3223E, SP3223E, MAX3232E, ICL3232E, SP3232E, LT1385, SP385E, IS3232E
- High Data Rate at 1000kbps Available on ZT32xxF Series

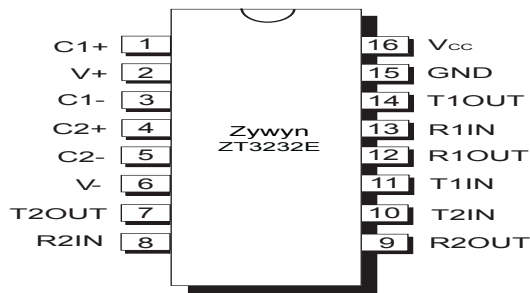
General Description

The ZT32xxE series devices are 3V powered EIA/TIA-232 and V.28/V.24 communication interfaces with low power requirements. They consist of two line drivers, two line receivers and the proprietary switch-capacitor regulated voltage converters. The ZT3220E has a 1Tx and 1Rx configuration. These devices operate from a single 3V to 5.5V power supply at the guaranteed data rate of 250k bits/sec with enhanced electrostatic discharge (ESD) protection in all RS232 I/O pins exceeding ± 15 kV EN61000-4-2 Air Gap Discharge and ± 8 kV EN61000-4-2 Contact Discharge.

The ZT3221E and ZT3223E features the AUTOGREEN (patent pending) proprietary function which automatically powers down the on-chip regulated voltage converters and driver circuits when an RS-232 cable is disconnected from the host interface or when a connected peripheral device is turned off.

Applications

- Battery-Powered And Hand-Held Applications
- Notebooks, Subnotebooks, and Palmtops
- Industrial and Embedded PCs
- Data Cables for Cell Phones and PDAs
- Terminal Adapters and POS terminals
- Peripherals interface
- Routers and HUBs



Product Selection Guide

Part Number	Power Supply	RS232 Drivers	RS232 Receivers	Data Rate (kbps)	15KV ESD IEC1000 4-2	Receiver Enable	SHUTDOWN Enable	AUTOGREEN Function	Number of Pins	Package Type
ZT3220E	+3V to +5.5V	1	1	250	RS232 I/O	YES	YES	NO	16	SSOP, TSSOP, WSOIC
ZT3221E	+3V to +5.5V	1	1	250	RS232 I/O	YES	YES	YES	16	SSOP, TSSOP
ZT3222E	+3V to +5.5V	2	2	250	RS232 I/O	YES	YES	NO	18, 20	18-WSOIC, 20-SSOP, 20-TSSOP,
ZT3232E	+3V to +5.5V	2	2	250	RS232 I/O	NO	NO	NO	16	NSOIC, WSOIC, SSOP, TSSOP, QFN
ZT3223E	+3V to +5.5V	2	2	250	RS232 I/O	YES	YES	YES	20	SSOP, TSSOP
ZT1385E	+3V to +5.5V	2	2	250	RS232 I/O	NO	YES	NO	18, 20	18-WSOIC, 20-SSOP



Absolute Maximum Ratings

These are stress ratings only and functional operation of the device at these ratings or any other above those indicated in the operation sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods of time may affect reliability.

Power Supply, (V_{CC}).....	-0.3V to +6.0V
V+	-0.3V to +7.0V
V-	+0.3V to -7.0V
V+ + V- 	+13.0V
I_{CC} (DC V_{CC} or GND current).....	± 100 mA
Input Voltages	
TxIN, GREEN, SHUTDOWN, EN	-0.3V to +6.0V
RxIN.....	± 25 V
Output Voltages	
TxOUT	± 15 V
RxOUT, IDLE	-0.3V to ($V_{CC} + 0.3$ V)
Short-Circuit Duration	
TxOUT	Continuous
Operating Temperature.....	-40°C to +85°C
Storage Temperature.....	-65°C to +150°C

Power Dissipation Per Package

16-pin SSOP (derate 7.20mW/°C above +70°C)...	584mW
16-pin nSOIC (derate 10.00mW/°C above +70°C)	720mW
16-pin WSOIC (derate 10.10mW/°C above +70°C)	787mW
16-pin TSSOP (derate 6.80mW/°C above +70°C)	556mW
16-pin PDIP (derate 11.20mW/°C above +70°C) ..	896mW
16-pin QFN (derate 24mW/°C above +70°C).....	2W
18-pin PDIP (derate 12.60mW/°C above +70°C) ..	962mW
18-pin WSOIC (derate 11.10mW/°C above +70°C)	850mW

Storage Considerations

Storage in a low humidity environment is preferred. Large high density plastic packages are moisture sensitive and should be stored in Dry Vapor Barrier Bags. Prior to usage, the parts should remain bagged and stored below 40°C and 60%RH. If the parts are removed from the bag, they should be used within 168 hours or stored in an environment at or below 20%RH. If the above conditions cannot be followed, the parts should be baked for 12 hours at 125°C in order to remove moisture prior to soldering. Zywyn ships product in Dry Vapor Barrier Bags with a humidity indicator card and desiccant pack. The humidity indicator should be below 30%RH. The MSL of this product is 3.

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Electrical Characteristics

Unless otherwise stated, $V_{CC} = +3.0V$ to $+5.0V$, $T_A = T_{min}$ to T_{max} , $C1$ to $C4 = 0.1\mu F$, typical values apply at $V_{CC} = +3.3V$ or $+5.0V$ and $T_A = 25^\circ C$.

Parameter	Condition	Min	Typ	Max	Units
TTL Logic Input TTL Logic Output RS-232 Input RS-232 Output Charge Pump Pin Power Pin	$T_1IN, T_2IN, \overline{GREEN}, \overline{SHUTDOWN}, \overline{EN}$ $R_1OUT, R_2OUT, \overline{IDLE}$ R_1IN, R_2IN T_1OUT, T_2OUT C_1P, C_1N, C_2P, C_2N $V_{CC}, V_{GND}, V_{DD}, V_{SS}$				
Charge Pump Caps Temp $0^\circ C$ to $+70^\circ C$ Temp $-40^\circ C$ to $+85^\circ C$ V_{CC} Voltage Range	C_1P, C_1N, C_2P, C_2N Commercial Grade Industrial Grade $V_{CC} = +5.0V$ Supply $V_{CC} = +3.3V$ Supply	0.1 0 -40 4.5 3	0.1 +25 +25 5 3.3	1 +70 +85 5.5 3.6	μF $^\circ C$ $^\circ C$ V V
Supply Current	TTL Inputs = V_{CC}/GND , RS-232 Input = float, $V_{CC} = 3.3V$ (For ZT3220E, ZT3222E, ZT3232E and ZT1385E)		0.5	1	mA
Supply Current, AUTOGREEN Disabled	$\overline{GREEN} = V_{CC}$, (For ZT3221E and ZT3223E); $\overline{SHUTDOWN} = V_{CC}$, (For ZT3221E, ZT3222E, ZT1385E and ZT3223E), TTL Inputs = V_{CC}/GND , RS-232 Input = float, $V_{CC} = 3.3V$		0.5	1	mA
Supply Current, AUTOGREEN Enabled	$\overline{GREEN} = GND$, (For ZT3221E and ZT3223E); $\overline{SHUTDOWN} = V_{CC}$, (For ZT3221E, ZT3222E, ZT1385E and ZT3223E), TTL Inputs = V_{CC}/GND , RS-232 Input = float, $V_{CC} = 3.3V$		1	10	μA
Supply Current, SHUTDOWN Enabled	$\overline{GREEN} = V_{CC}/GND$, (For ZT3221E and ZT3223E); $\overline{SHUTDOWN} = GND$, (For ZT3221E, ZT3222E, ZT1385E and ZT3223E), TTL Inputs = V_{CC}/GND , RS-232 Inputs = float, $V_{CC} = 3.3V$		1	10	μA
TTL LOGIC Input Input Threshold Low Input Threshold High Input Threshold High Input Hysteresis Input Leakage Current Input Leakage Current	$V_{CC} = +5.0V$ Supply $V_{CC} = +3.3V$ Supply $V_{IN} = V_{CC}$ and GND, $TIN, \overline{EN}, \overline{GREEN}, \overline{SHUTDOWN}$ $V_{IN} = V_{CC}$ and GND, TIN (For ZT1385E)	2.4 2	0.5 ± 0.01	0.8 ± 1	V V V V μA μA
TTL LOGIC Output Output Voltage Low Output Voltage High Output Leakage Current	$I_{OUT} = 1.6mA$ $I_{OUT} = -1.0mA$ Receiver Outputs Disabled, $V_{OUT} = V_{CC}$ or GND, $\overline{SHUTDOWN} = GND, \overline{EN} = V_{CC}$	$V_{CC}-0.6$	$V_{CC}-0.1$ ± 0.05	0.4 ± 10	V V μA
Receiver Input Input Voltage Range Input Threshold Low Input Threshold High Input Hysteresis Input Resistance	$T_A = T_{min} - T_{max}$ $T_A = 25^\circ C, V_{CC} = 5.0V$ $T_A = 25^\circ C, V_{CC} = 3.3V$ $V = 25^\circ C$ $T_A = 25^\circ C$ $V_{IN} = \pm 25V, T_A = 25^\circ C$	-25 0.8 0.6	1.5 1.2 0.5	25 2.4 7	V V V V k Ω
Transmitter Output Output Voltage Swing Output Resistance Output Short-Circuit Current Output Leakage Current	$R_L = 3k\Omega$, All Outputs are loaded $V_{CC} = V_{DD} = V_{SS} = GND, V_{OUT} = \pm 2V$ $V_{OUT} = GND$ Transmitter Disabled, $V_{OUT} = \pm 12V$	± 5 300	 ± 5	 ± 60	V Ω mA μA

Parameter	Condition	Min	Typ	Max	Units
Timing Characteristics					
Maximum Data Rate Refers to Figure 1 and 2.	$R_L = 3k\Omega$, $C_L = 1000pF$, One Transmitter Switching, $T_A = 25^\circ C$	250			kbps
Transition-Region Slew Rate	$R_L = 3\sim 7k\Omega$, $CL = 150pF$ to $1000pF$, One Transmitter Switching, $T_A = 25^\circ C$, Measured from $3V$ to $-3V$ or $-3V$ to $3V$	6		30	V/ μs
Receiver Propagation t_{PLH}	$C_L = 150pF$		0.15		μs
Receiver Propagation t_{PHL}	$C_L = 150pF$		0.15		μs
Receiver Skew	$t_{PHL} - t_{PLH}$		50		ns
Receiver Output Enable Time	For ZT3220E, ZT3221E, ZT3222E, ZT3223E only		0.2		μs
Receiver Output Disable Time	For ZT3220E, ZT3221E, ZT3222E, ZT3223E only		0.2		μs
AUTOGREEN Timing					
Receiver Input to \overline{IDLE} Output High	For ZT3221E and ZT3223E only		1		μs
Receiver Input to \overline{IDLE} Output Low	For ZT3221E and ZT3223E only		30		μs
Power Save Mode to Transmitter Enabled	For ZT3221E and ZT3223E only		100		μs
ESD Tolerance					
ESD HBM	RS-232 Inputs and Outputs		± 15		kV
EN61000-4-2 Contact Discharge	RS-232 Inputs and Outputs		± 8		kV
EN61000-4-2 Air Gap Discharge	RS-232 Inputs and Outputs		± 15		kV

Product Cross Reference

Part Number	Pin-to-Pin Cross MAXIM	Pin-to-Pin Cross Intersil	Pin-to-Pin Cross TI	Pin-to-Pin Cross ST-M	Pin-to-Pin Cross EXAR
ZT3220E	MAX3220E MAX3220	n/a	MAX3220E	n/a	SP3220E
ZT3221E	MAX3221E MAX3221	ICL3221E ICL3221	MAX3221E MAX3221	n/a	n/a
ZT3222E	MAX3222E MAX3222	ICL3222E ICL3222	MAX3222E MAX3222	ST3222E ST3222	SP3222E SP3222EB
ZT3232E	MAX3232E MAX3232	ICL3232E ICL3232	MAX3232E MAX3232	ST3232E ST3232	SP3232E SP3232EB
ZT3223E	MAX3223E MAX3223	ICL3223E ICL3223	MAX3223E MAX3223	n/a	SP3223E SP3223EB
ZT1385E	n/a	n/a	LT1385	n/a	SP385E

Pin Description

Pin Numbers								Name	Description
ZT3220E	ZT3221E	ZT3222E		ZT3232E	ZT1385E		ZT3223E		
16 Pins	16 Pins	18 Pins	20 Pins	16 Pins*	18 Pins	20 Pins	20 Pins		
1	1	1	1	–	–	–	1	EN	Receiver Enable. Logic low for Normal operation. Logic high to force the receiver outputs into high impedance state
2	2	2	2	1	2	2	2	C1+	Positive terminal of the bootstrapped voltage switch capacitor
3	3	3	3	2	3	3	3	V+	Regulated +5.4V output generated by the voltage converter
4	4	4	4	3	4	4	4	C1-	Negative terminal of the bootstrapped voltage switch capacitor
5	5	5	5	4	5	5	5	C2+	Positive terminal of the inverted voltage switch capacitor
7	7	7	7	6	7	7	7	V-	Regulated –5.7V output generated by the voltage converter
6	6	6	6	5	6	6	6	C2-	Negative terminal of the inverted voltage switch capacitor
8	8	14	16	13	14	16	16	R1 IN	First RS232 receiver input
–	–	9	9	8	9	9	9	R2 IN	Second RS232 receiver input
9	9	13	15	12	13	15	15	R1 OUT	First TTL/CMOS receiver output
–	–	10	10	9	10	12	10	R2 OUT	Second TTL/CMOS receiver output
11	11	12	13	11	12	14	13	T1 IN	First TTL/CMOS transmitter input
–	–	11	12	10	11	13	12	T2 IN	Second TTL/CMOS transmitter input
13	13	15	17	14	15	17	17	T1 OUT	First RS232 transmitter output
–	–	8	8	7	8	8	8	T2 OUT	Second RS232 transmitter output
–	10	–	–	–	–	–	11	IDLE	TTL/CMOS output indicating AUTOGREEN or SHUTDOWN status
16	16	18	20	–	18	20	20	SHUTDOWN	Shutdown control. A logic LOW to disable drivers and voltage converter
–	12	–	–	–	–	–	14	GREEN	A logic HIGH to override AUTO-GREEN circuitry keeping transmitters ON. (SHUTDOWN must be HIGH)
14	14	16	18	15	16	18	18	GND	Ground
15	15	17	19	16	17	19	19	V _{CC}	+3V to +5.5V Supply Voltage
10, 12	–	–	11, 14	–	1	1, 10, 11	–	NC	No connect

*Pin-outs for NSOIC, WSOIC, SSOP and TSSOP packages only.

Pin Description

ZT3232LEEQ (5x5 16-QFN Package)

Pin Number	Pin Name	Pin Function
1	C1-	Negative terminal of the bootstrapped voltage switch capacitor
2	C2+	Positive terminal of the inverted voltage switch capacitor
3	C2-	Negative terminal of the bootstrapped voltage switch capacitor .
4	V-	Regulated -5.7V output generated by the voltage converter
5	T2OUT	Second RS232 transmitter output
6	R2IN	Second RS232 receiver input.
7	R2OUT	Second TTL/CMOS receiver output.
8	T2IN	Second TTL/CMOS transmitter input.
9	T1IN	First TTL/CMOS transmitter input
10	R1OUT	First TTL/CMOS receiver output.
11	R1IN	First RS232 receiver input.
12	T1OUT	First RS232 transmitter output
13	GND	Ground.
14	VCC	+3V to +5.5V Supply Voltage
15	C1+	Positive terminal of the bootstrapped voltage switch capacitor
16	V+	Regulated +5.4V output generated by the voltage onverter

Circuit Description

Proprietary Switch-Capacitor Regulated Voltage Converter

Different from other suppliers, Zywyn uses a patent pending switch-capacitor voltage-controlled source and sink current generators design to provide powerful bipolar voltages to maintain compliant EIA/RS232 levels regardless of power supply fluctuations. The design consists of an internal regulated oscillator, a two phase clock cycling, regulated complementary MOS switches, fast switching diode and switch capacitors.

The switch capacitor bi-directional current generators operate with Zywyn's proprietary smartly regulated complementary MOS switches and fast switching diode from its proprietary high voltage process technology. The efficiency of these bi-directional current generators is well over 70%. The switching frequency is generated by an internal oscillator and regulated by the current loads. The switch capacitor pump design delivers higher negative bucked voltage than the positive boosted voltage to achieve a balanced voltage controlled source and sink current generators resulting a balanced bipolar voltage supplies to the chip.

With its unique proprietary design technique, Zywyn's interface product series provide a better power efficient, stable and compliant EIA/RS232 levels with superior low power consumption.

Controlled Power-Down

The ZT3220E, ZT3221E, ZT3222E, and ZT3223E have a low-power shutdown mode controlled by the `SHUTDOWN` pin. During shutdown the driver output and the switch-capacitor regulated voltage converter are disabled with the supply current falls to less than 1 μ A.

The ZT3221E and ZT3223E use Zywyn's patent pending `AUTOGREEN` circuitry to set/reset latches, which enable the circuit shutdown function when a RS232 cable is disconnected or when the peripheral is turned off and reduce the power supply drain to a 1 μ A supply current. When a RS232 cable is connected or when the peripheral is enabled, the devices will automatically become active again.

ESD Immunity

Electro-Static Discharge (ESD) is an important factor when implementing a serial port into a system. In some applications, it is crucial that the ESD protection for the system must meet a certain tolerance level. Since RS232 transceiver devices are exposed to the outside world, there are many environmental factors that can effect the serial port and even subject it to transients that could potentially damage the transceiver itself.

The RS232 transceiver is usually routed from the serial port connector to the transceiver IC through the metal trace on the printed circuit board. This trace will have some small amount of resistance that will add some protection in terms

of limiting transient current to the IC. However for added voltage protection, transient voltage suppressors (TVS) or transzorbs, which are back-to-back diode arrays clamp, are usually necessary to protect the serial port circuitry.

To further reduce cost within their system, more engineers are requiring higher ESD tolerances from the transceiver ICs themselves without having to add costly TVS circuitry. Zywyn's RS232 transceivers includes built-in transient voltage suppression where external ESD circuitry is not necessary to meet the MIL-STD-883, Method 3015, Human Body Model and the EN61000-4-2 Air/Contact Discharge tests.

The Human Body Model has been the generally accepted ESD testing method for semiconductors. This test is intended to simulate the human body's potential to store electrostatic energy and discharge it to an integrated circuit upon close proximity or contact. This method will test the IC's capability to withstand an ESD transient during normal handling such as in manufacturing areas where the ICs tend to be handled frequently.

EN61000-4-2 is used for testing ESD on equipment and systems. For system manufacturers, they must guarantee a certain amount of ESD protection since the system itself is exposed to the outside environment and human presence. EN61000-4-2 specifies that the system is required to withstand an amount of static electricity when ESD is applied to exposed metal points and surfaces of the equipment that are accessible to personnel during normal usage. The transceiver IC receives most of the ESD current when the ESD source is applied to the connector pins.

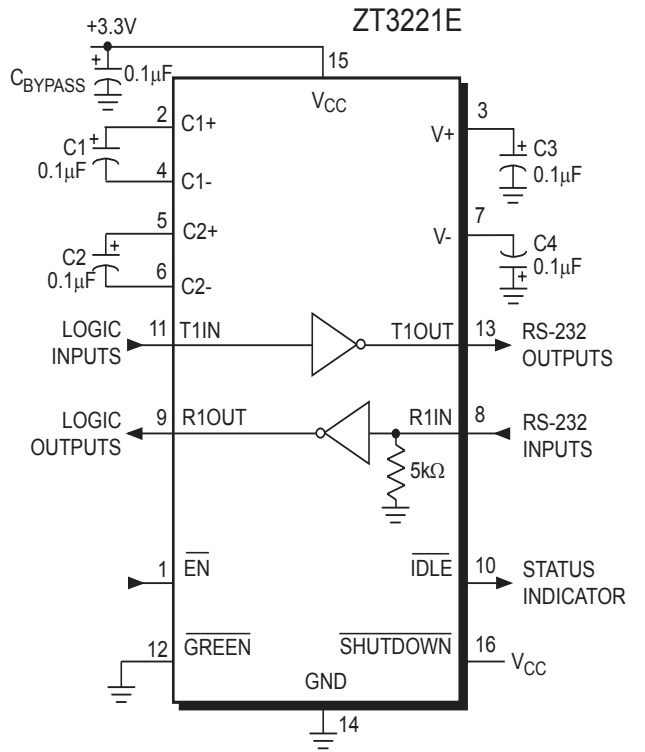
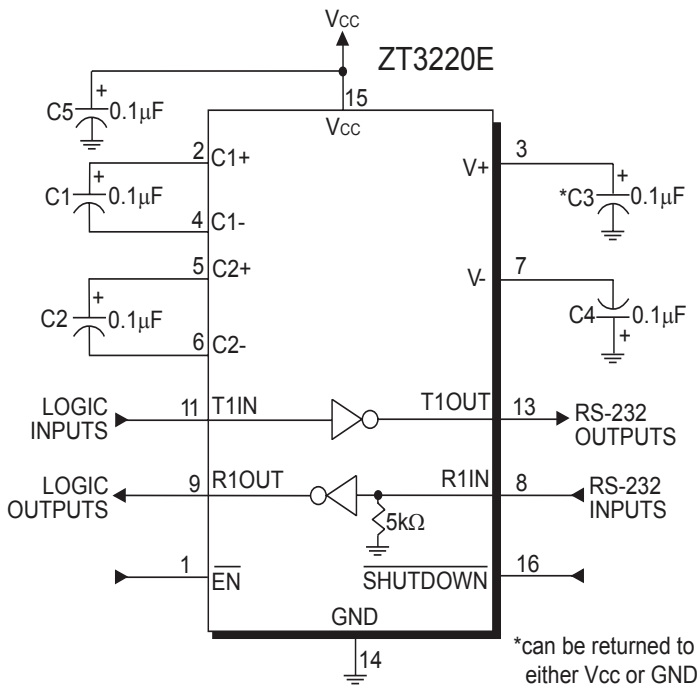
There are two methods within EN61000-4-2, the Air Discharge method and the Contact Discharge method. With the Air Discharge Method, an ESD voltage is applied to the equipment under test through air, which simulates an electrically charged person ready to connect a cable onto the rear of the system and the high energy potential on the person discharges through an arcing path to the rear panel of the system before he or she even touches the system. The Contact Discharge Method applies the ESD current directly to the EUT. This method was devised to reduce the unpredictability of the ESD arc. The discharge current rise time is constant since the energy is directly transferred without the air-gap arc inconsistencies.

Zywyn's RS232 transceivers meets and exceeds the minimum criteria for EN61000-4-2 with ± 15 kV for Air Gap Discharge and ± 8 kV for Contact Discharge.

Operation Status	$\overline{\text{GREEN}}$	$\overline{\text{SHUTDOWN}}$	$\overline{\text{EN}}$	Signal at $R_x\text{IN}$	$\overline{\text{IDLE}}$	$T_x\text{OUT}$	$R_x\text{OUT}$
Shutdown	don't care	0	0	present	1	tri-state	active
	don't care	0	0	not present	0	tri-state	active
	don't care	0	1	present	1	tri-state	tri-state
	don't care	0	1	not present	0	tri-state	tri-state
Normal without $\overline{\text{GREEN}}$	1	1	0	present	1	active	active
	1	1	0	not present	0	active	active
	1	1	1	present	1	active	tri-state
	1	1	1	not present	0	active	tri-state
Normal with $\overline{\text{GREEN}}$	0	1	0	present	1	active	active
	0	1	0	not present	0	tri-state	tri-state
	0	1	1	present	1	active	tri-state
	0	1	1	not present	0	tri-state	tri-state

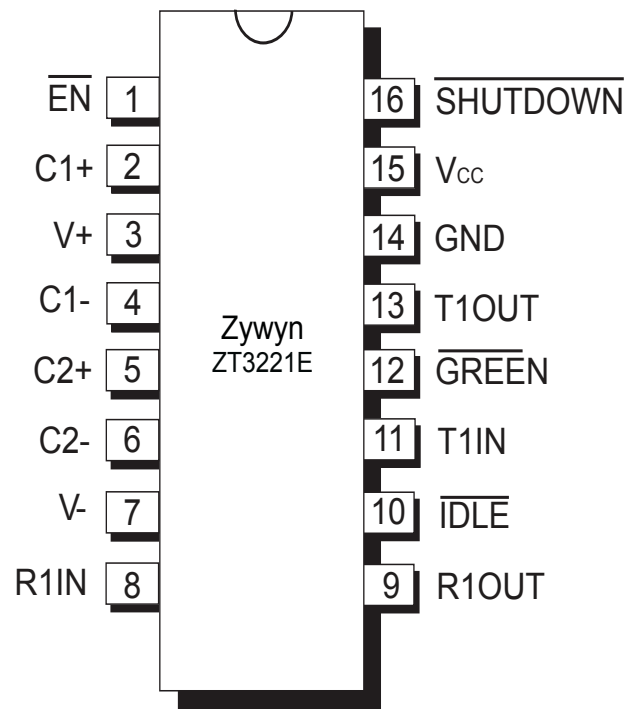
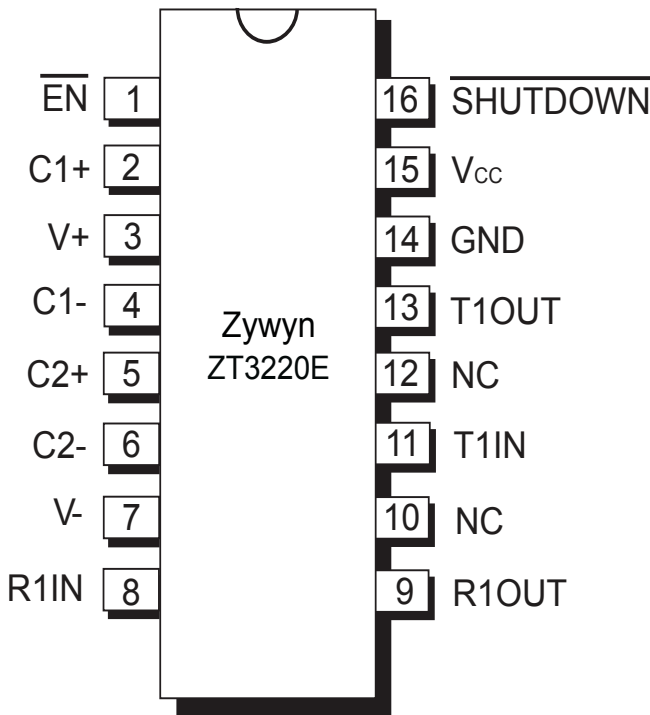
Table 1. ZT32xxE Truth Table

Typical Application Circuits and Pin Configuration

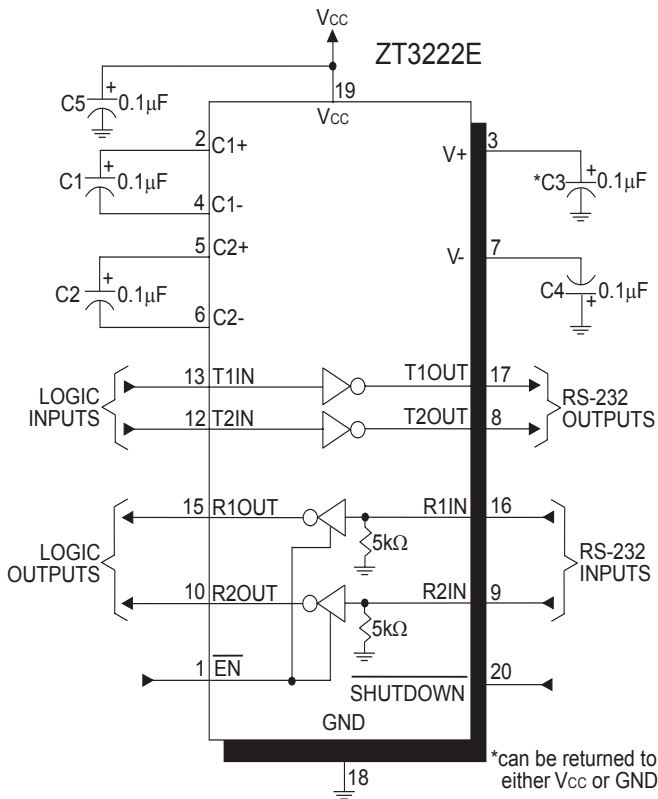


16-pin SSOP/TSSOP/WSOIC

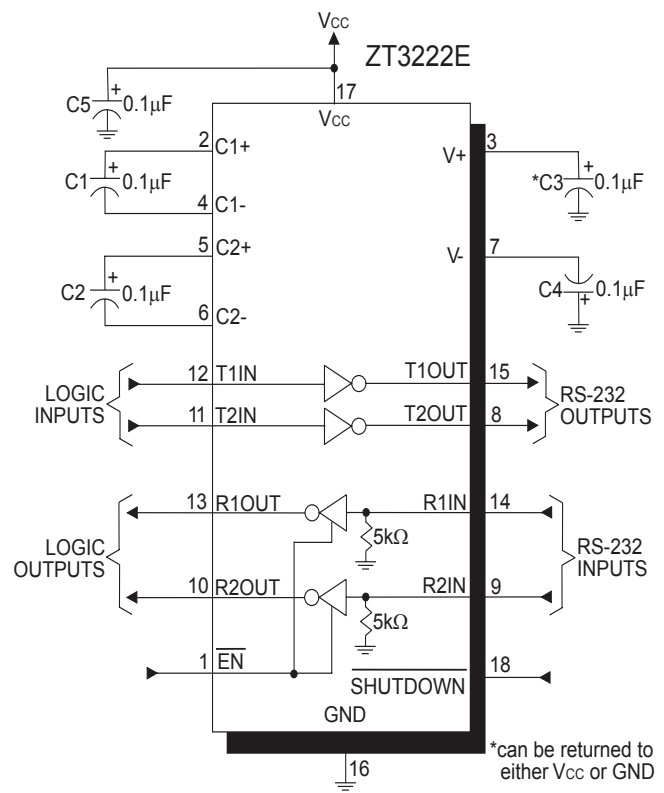
16-pin SSOP/TSSOP



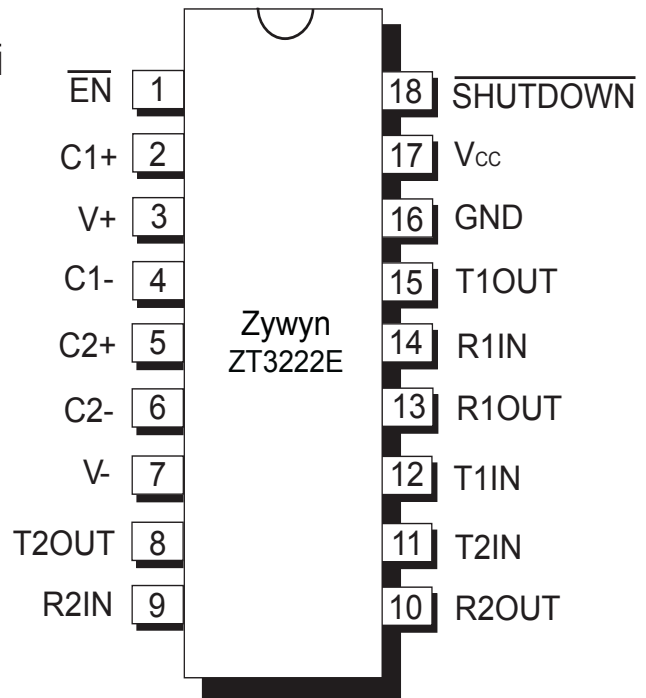
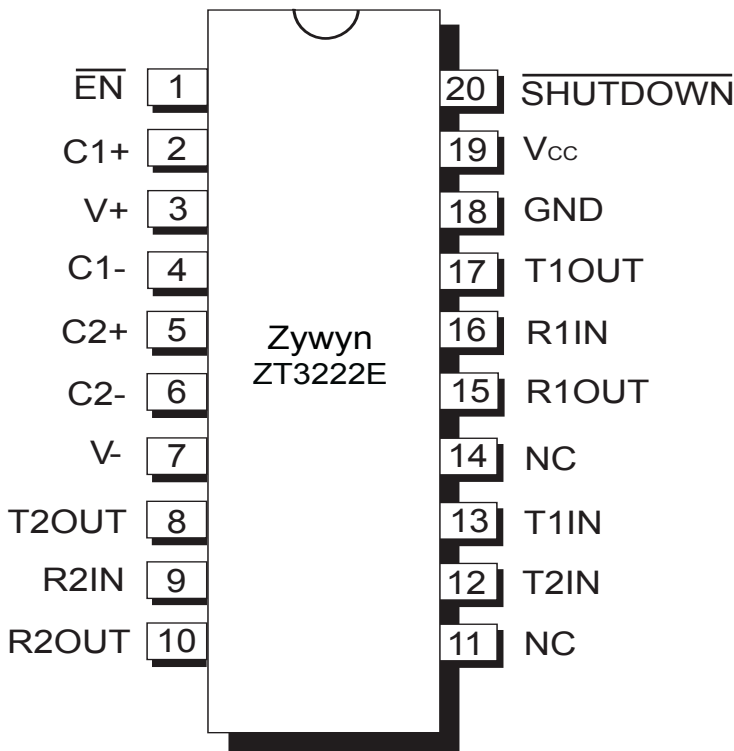
Typical Application Circuits and Pin Configuration



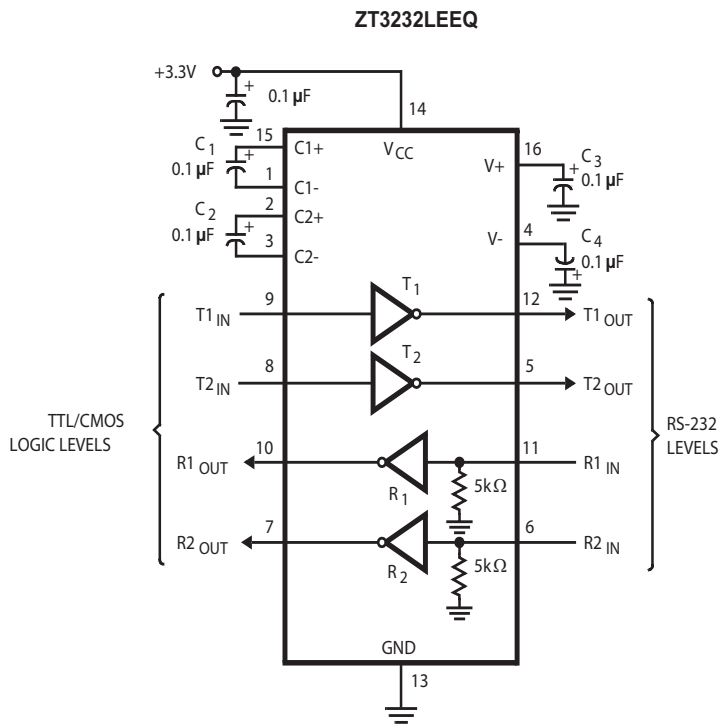
20-pin SSOP/TSSOP



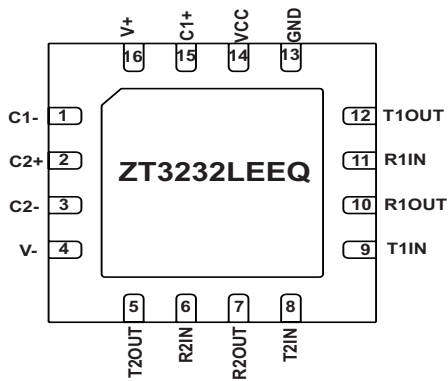
18-pin WSOIC



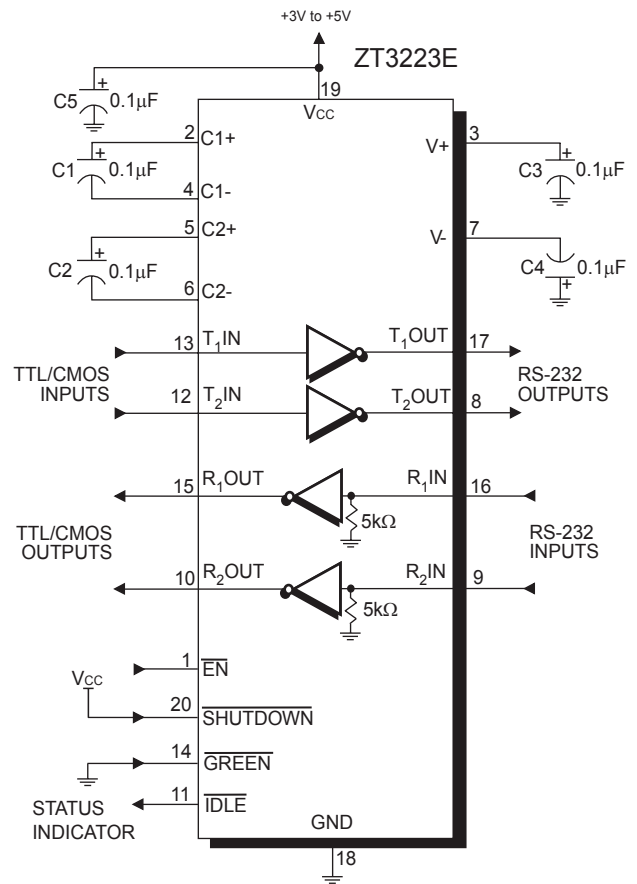
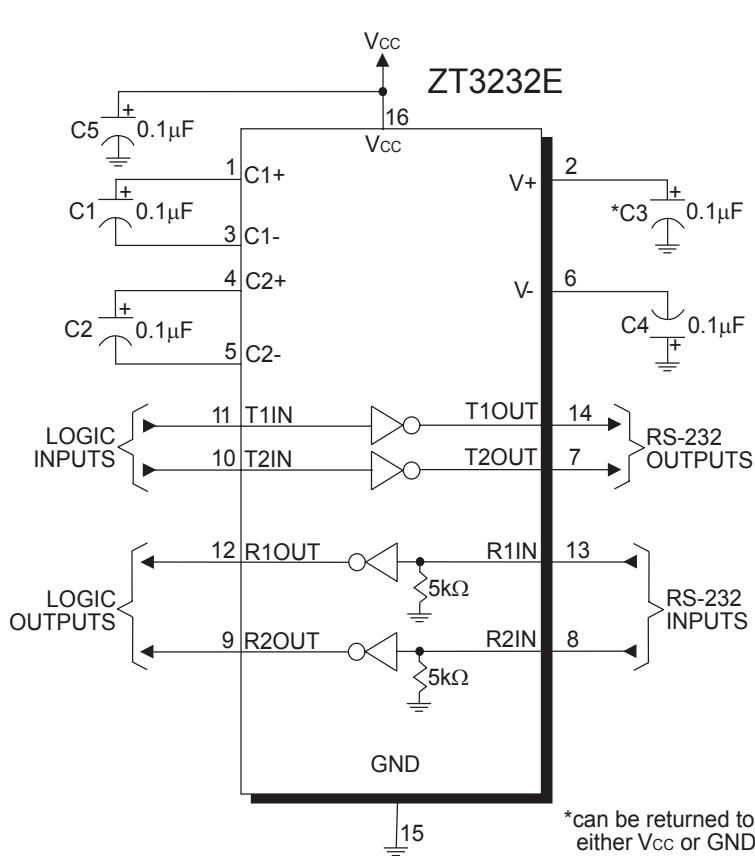
Typical Application Circuits and Pin Configuration



16-pin QFN

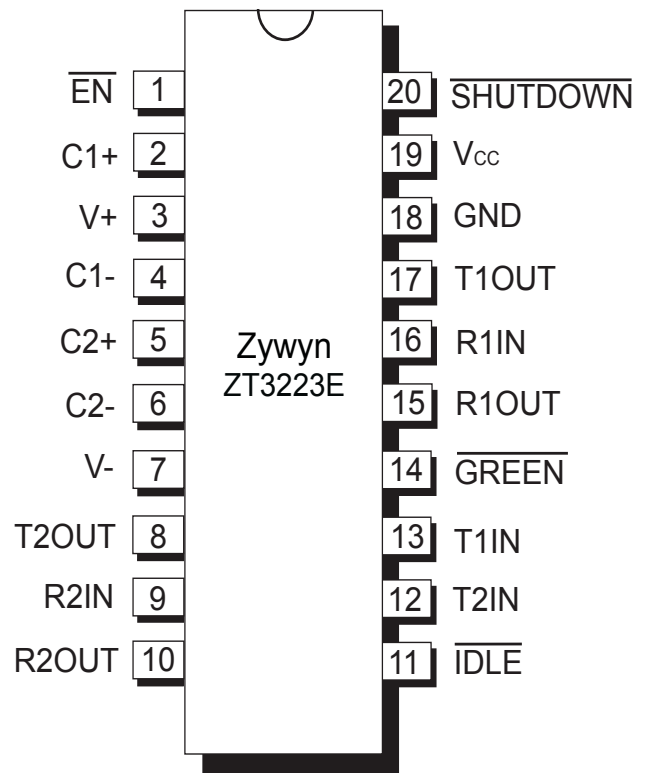
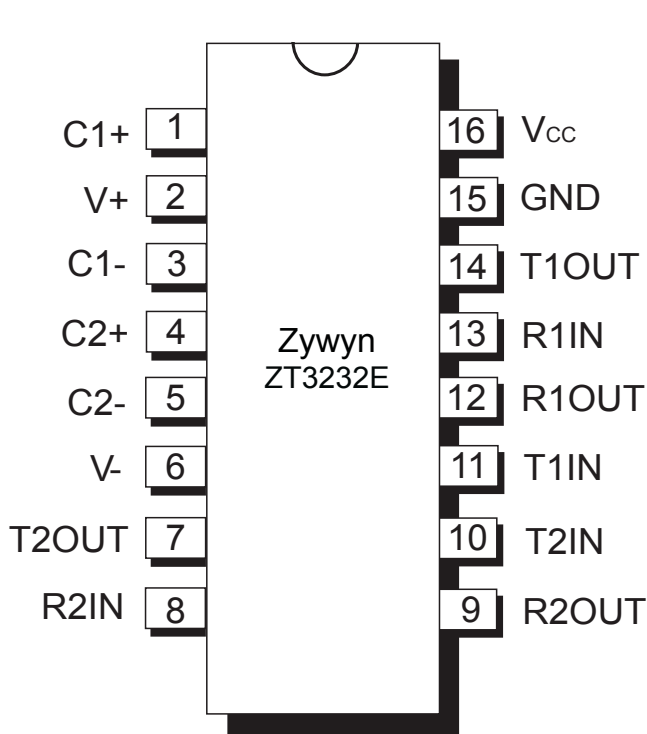


Typical Application Circuits and Pin Configuration

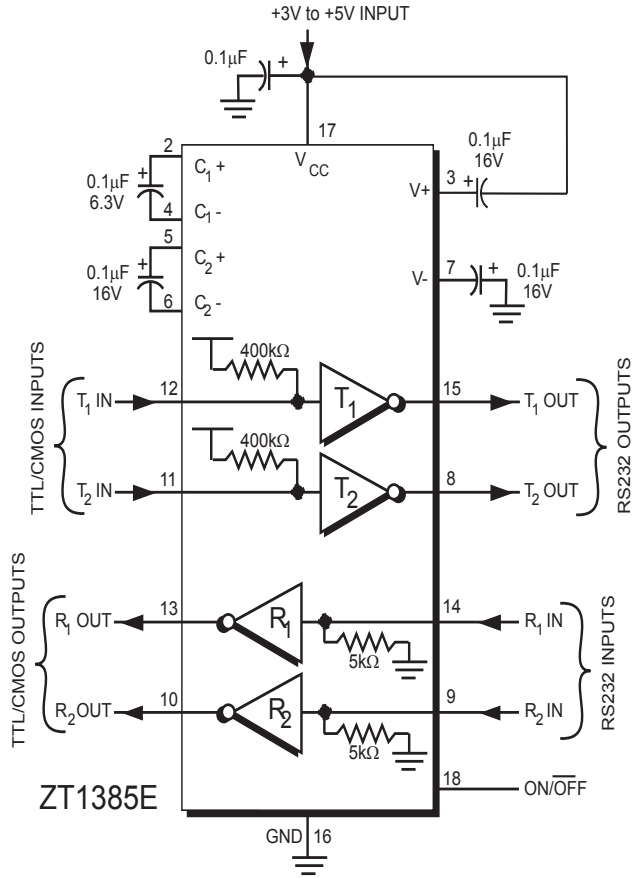


16-pin SSOP/TSSOP/NSOIC/WSOIC

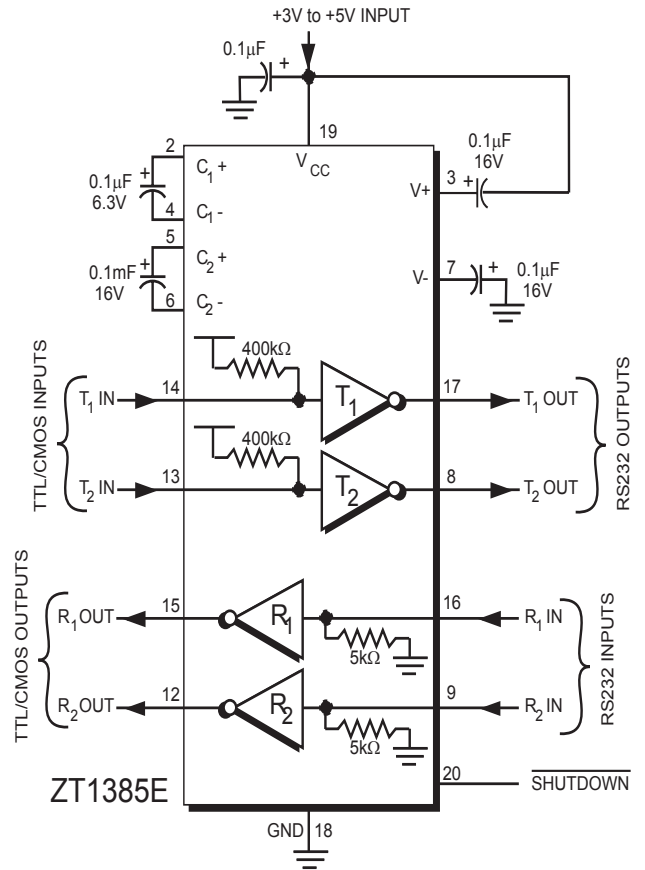
20-pin SSOP/TSSOP



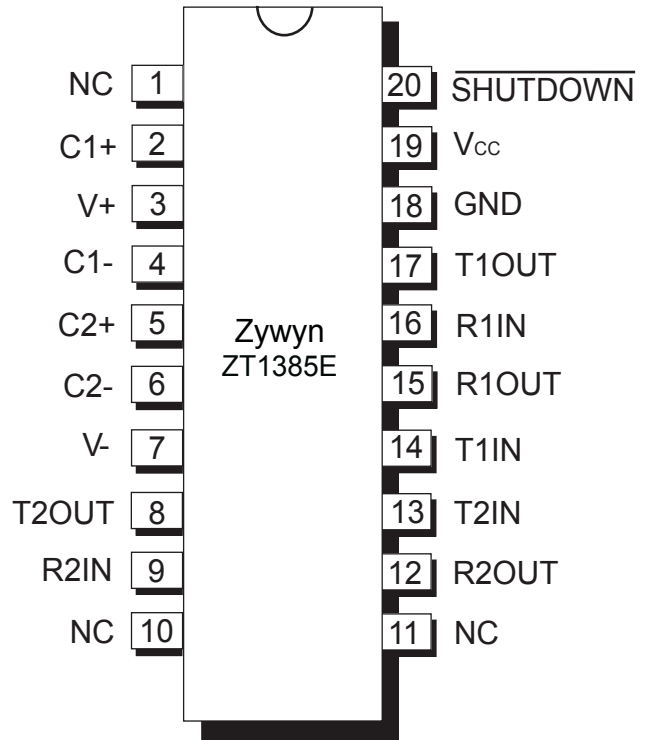
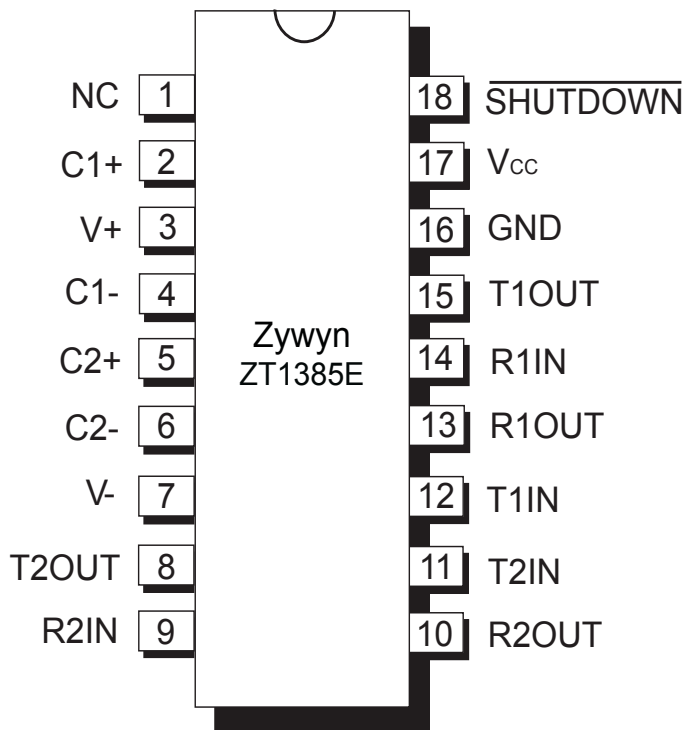
Typical Application Circuits and Pin Configuration



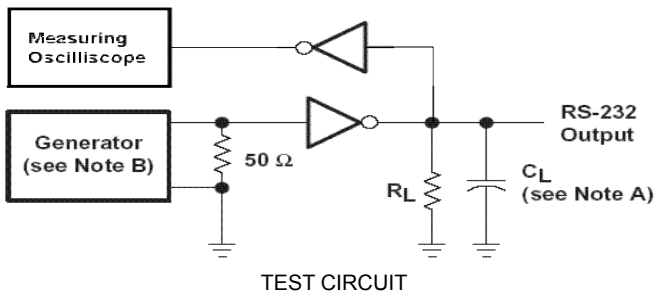
18-pin WSOIC



20-pin SSOP



Typical Test Circuits



Maximum Data Rate Test Circuit

Notes:

A. $R_L = 3k\Omega$, $C_L = 1000pF$, $T_A = 25^\circ C$,

One Driver Switching.

B. The pulse generator had the following characteristics:

PRR = 250 kbps, $Z_o = 50\Omega$, 50% duty cycle,

T_r & $T_f \leq 10ns$.

C. SHUTDOWN = V_{CC} when applicable.

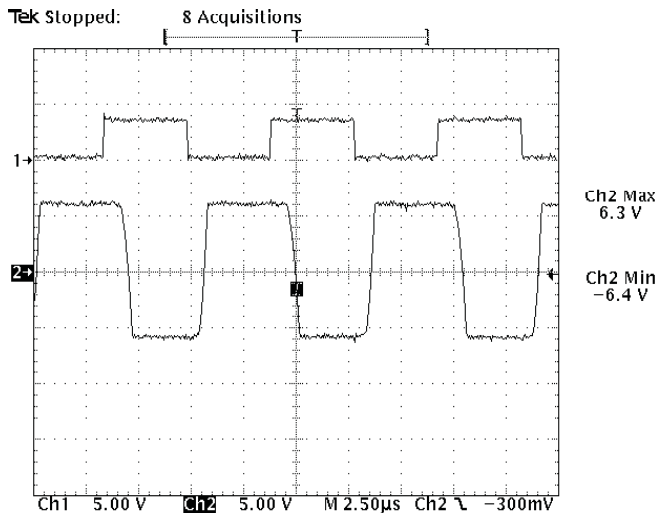


Figure 1. ZT32xxE TxIN to TxOut (no load) at 250kbps waveform

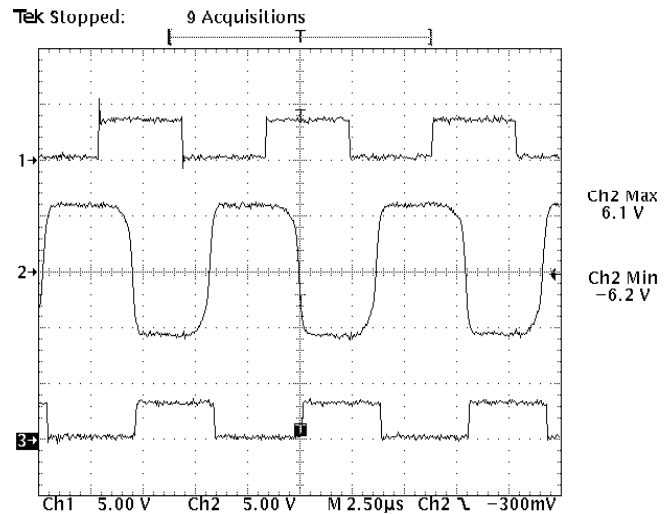


Figure 2. ZT32xxE TxIN to TxOut to RxOut (loopback to Rx with 1000pF load) at 250kbps waveform

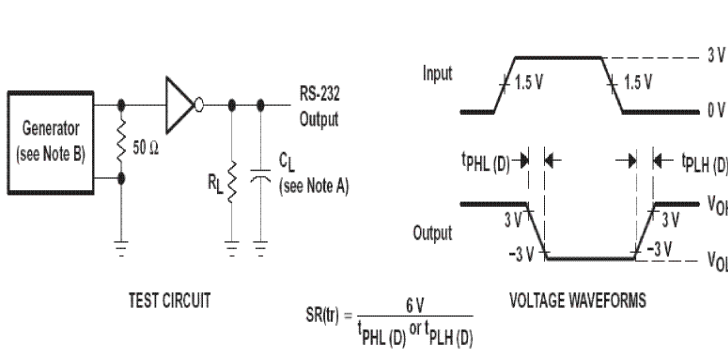
RS232 Signal Characteristics

Figure 1 shows the normal RS232 transceiver function with a TTL/CMOS signal applied to the input on channel 1 and the resultant RS232 output shown on channel 2. This figure shows a typical RS232 line driver output without loading. In other words, this is the open circuit RS232 output voltage. The charge pump voltage converter efficiently converts the necessary voltage for the driver's output transistors so that the RS232 output is close to the ideal rail voltage of 6.6V.

Figure 2 shows the RS232 transceiver function using the TTL/CMOS input on channel 1 while showing the RS232 output on channel 2. This figure shows the RS232 signal while the output is loaded with 3kohms and 1000pF. The resistive load is the receiver's input impedance as the driver's output is looped back to the

receiver's input. The resultant output on channel 3 is the receiver's TTL/CMOS output. While loaded with a typical RS232 load, the driver's output level only drops 0.2V from its open circuit voltage while running at 250kbps. The RS-232 output on channel 2 also shows good signal integrity while at the high data rates, which allows the receiver to process the signal with minimum skew and delay. Zywyn's low-drop driver circuitry working with its efficient voltage regulator allows superior line driving capability with the bonus of $\pm 15kV$ ESD immunity.

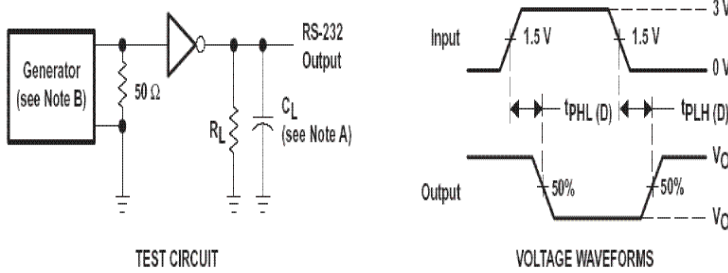
Typical Test Circuits



Driver Transition-Region Slew Rate Test Circuit

Notes:

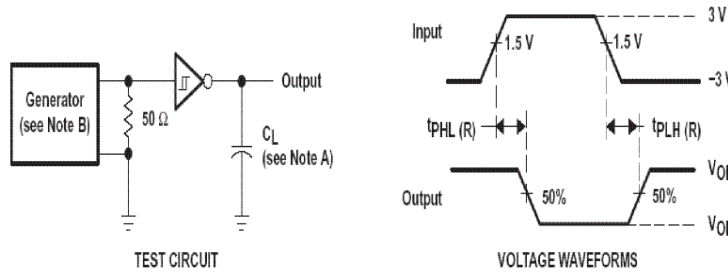
- A. $R_L = 3k\sim 7k\Omega$, $C_L = 150pF$ to $1000pF$, One Driver Switching, $T_A = 25^\circ C$, Measured from +3V to -3V or -3V to +3V.
- B. The pulse generator had the following characteristics:
 $PRR = 250$ kbps, $Z_o = 50\Omega$, 50% duty cycle, T_r & $T_f \leq 10ns$.
- C. $SHUTDOWN = V_{CC}$ when applicable.



Driver Propagation (t_{PHL} & t_{PLH}) Test Circuit

Notes:

- A. All drivers loaded with $R_L = 3k\Omega$, $C_L = 1000pF$.
- B. The pulse generator had the following characteristics:
 $PRR = 250$ kbps, $Z_o = 50\Omega$, 50% duty cycle, T_r & $T_f \leq 10ns$.
- C. $SHUTDOWN = V_{CC}$ when applicable.



Receiver Propagation Delay Times Test Circuit

Notes:

- A. $C_L = 150pF$, including probe and jig capacitance.
- B. The pulse generator had the following characteristics:
 $PRR = 250$ kbps, $Z_o = 50\Omega$, 50% duty cycle, T_r & $T_f \leq 10ns$.
- C. $SHUTDOWN = V_{CC}$ when applicable.

Package Information

NOTE :

1. CONTROLLING DIMENSION : mm
2. LEAD FRAME MATERIAL : COPPER 194
3. DIMENSION "D" DOES NOT INCLUDE MOLD FLASH, TIE BAR BURRS AND GATE BURRS. MOLD FLASH, TIE BAR BURRS AND GATE BURRS SHALL NOT EXCEED 0.006[0.15mm] PER END DIMENSION "E1" DOES NOT INCLUDE INTERLEAD FLASH. INTERLEAD FLASH SHALL NOT EXCEED 0.010[0.25mm] PER SIDE.
4. DIMENSION "b" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.003[0.08mm] TOTAL IN EXCESS OF THE "b" DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD TO BE 0.0028[0.07mm]
5. TOLERANCE : ±0.010[0.25mm] UNLESS OTHERWISE SPECIFIED.
6. OTHERWISE DIMENSION FOLLOW ACCEPTABLE SPEC.
7. REFERENCE DOCUMENT : JEDEC SPEC MO-150AC

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	—	—	2.00	—	—	0.079
A1	0.05	—	0.15	0.002	—	0.006
A2	1.65	1.75	1.85	0.065	0.069	0.073
b	0.22	0.30	0.38	0.0086	0.012	0.015
c	0.09	0.15	0.25	0.0035	0.006	0.0098
D	5.90	6.20	6.50	0.232	0.244	0.256
E	7.40	7.80	8.20	0.291	0.307	0.323
E1	5.00	5.30	5.60	0.197	0.209	0.220
e	—	0.65	—	—	0.0256	—
L	0.55	0.75	0.95	0.022	0.030	0.037
φ	0"	4"	8"	0"	4"	8"
y	—	—	0.10	—	—	0.004

16-pin SSOP

CUSTOMER :		ZYWYN CORPORATION	
APPROVED BY	DATE	TITLE:	
DRAW BY: <i>Jesmin Liu</i>	01/25/02	16L SSOP PACKAGE OUTLINE DRAWING (BODY SIZE: 5.3mm)	
CHECK BY: <i>Edward Yang</i>	01/25/02	DWG. NO.	PO-SSOP-016
APPROVAL: <i>Jack Tu</i>	01/25/02	REV.	0
APPROVAL: <i>Jack Tu</i>	01/25/02	UNIT :	mm
		SCALE :	12/1
		SHEET :	1 OF 1

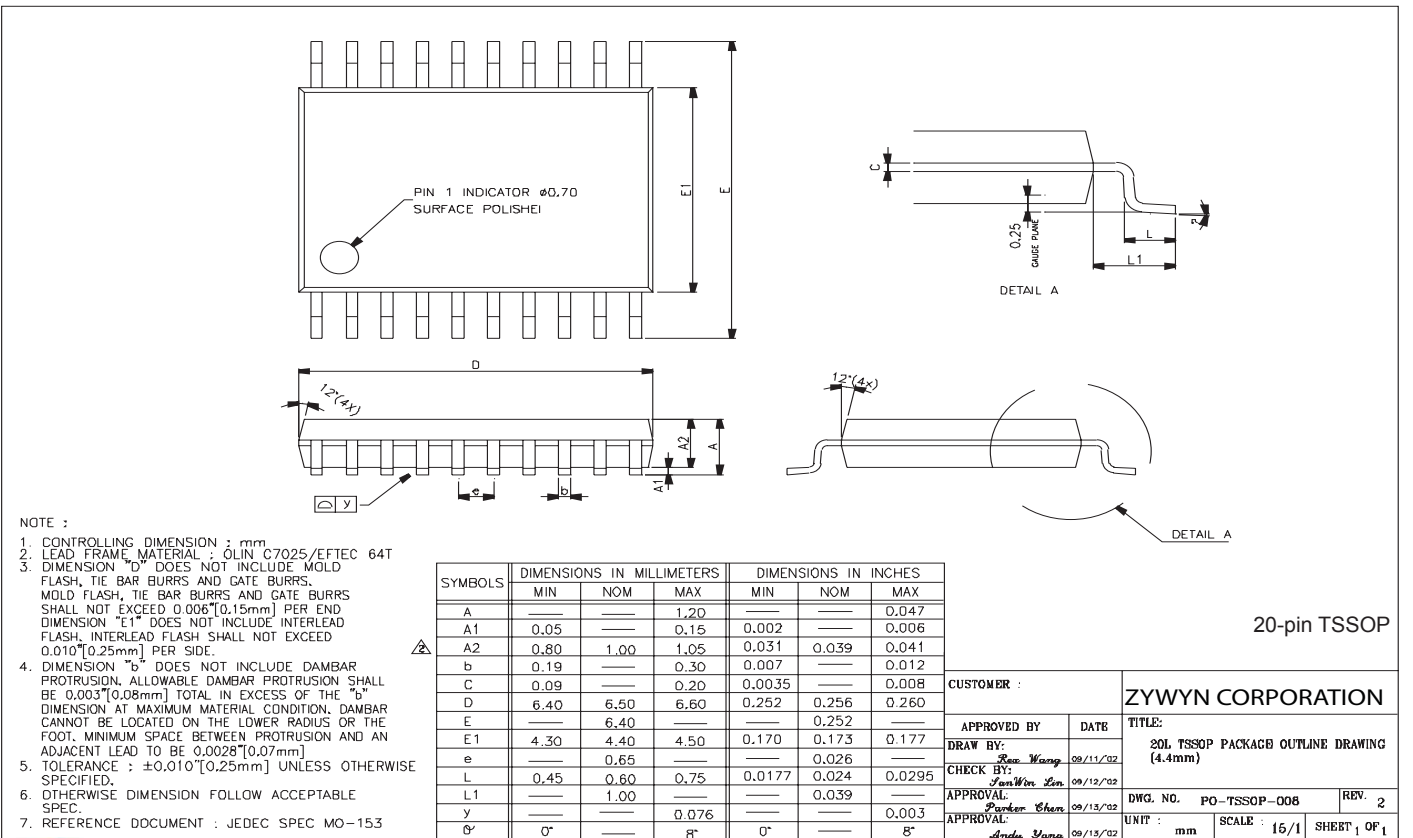
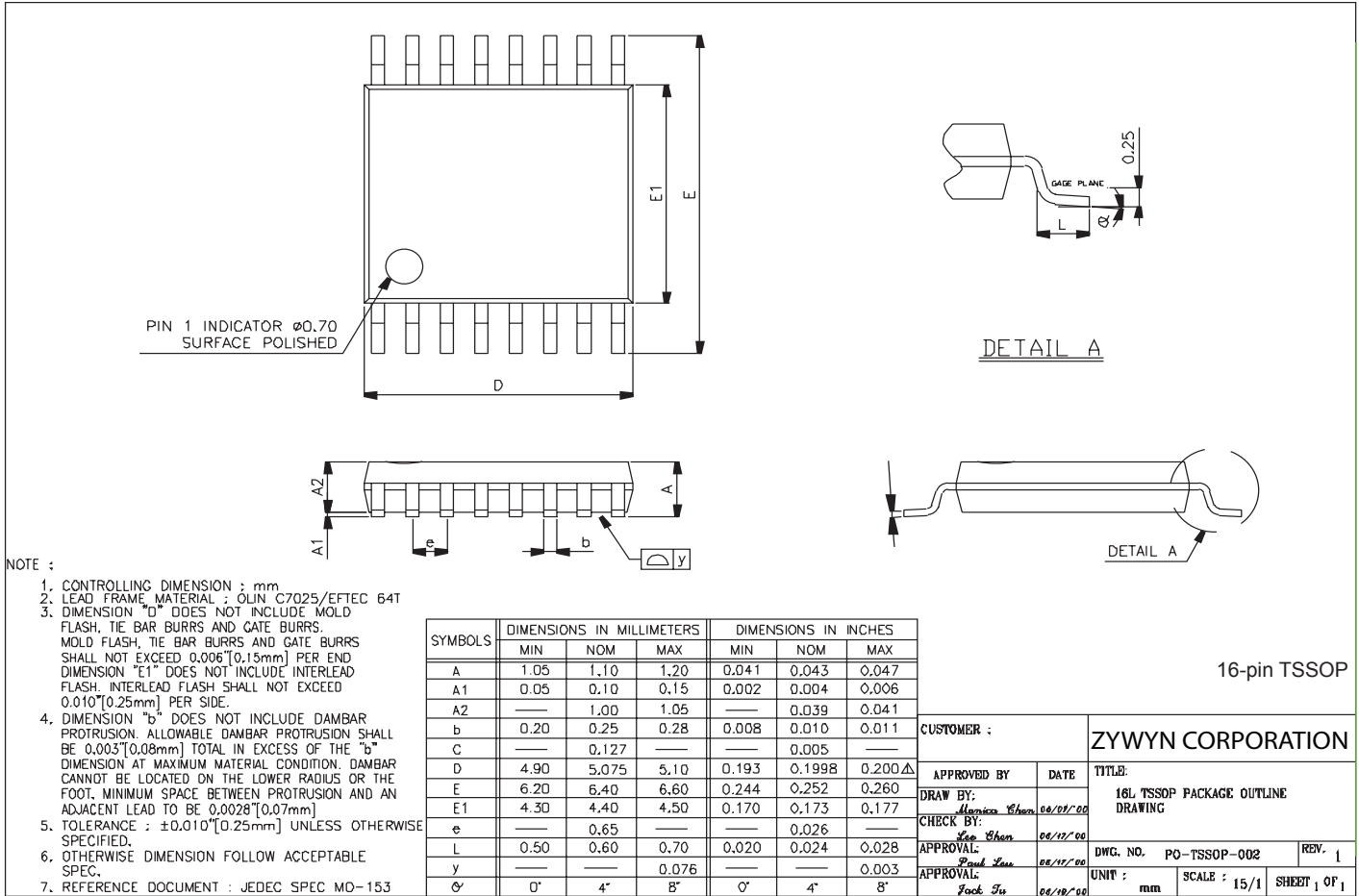
NOTE :

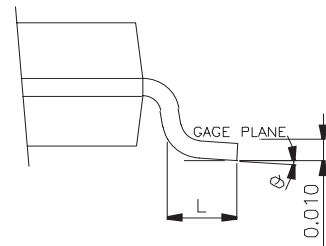
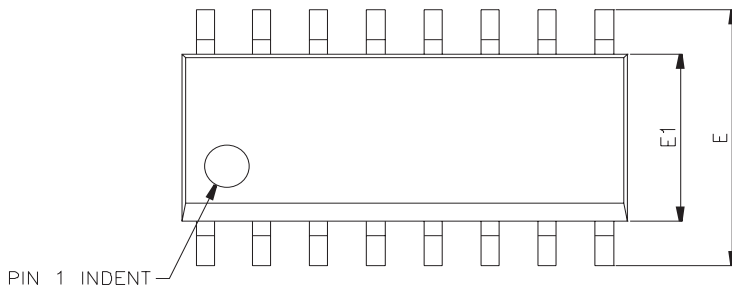
1. CONTROLLING DIMENSION : INCH
2. LEAD FRAME MATERIAL : COPPER 194
3. DIMENSION "D" DOES NOT INCLUDE MOLD FLASH, TIE BAR BURRS AND GATE BURRS. MOLD FLASH, TIE BAR BURRS AND GATE BURRS SHALL NOT EXCEED 0.006[0.15mm] PER END DIMENSION "E1" DOES NOT INCLUDE INTERLEAD FLASH. INTERLEAD FLASH SHALL NOT EXCEED 0.010[0.25mm] PER SIDE.
4. DIMENSION "b" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.003[0.08mm] TOTAL IN EXCESS OF THE "b" DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD TO BE 0.0028[0.07mm]
5. TOLERANCE : ±0.010[0.25mm] UNLESS OTHERWISE SPECIFIED.
6. OTHERWISE DIMENSION FOLLOW ACCEPTABLE SPEC.
7. REFERENCE DOCUMENT : JEDEC SPEC MO-150

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	—	—	2.00	—	—	0.079
A1	0.05	—	—	0.002	—	—
A2	—	1.75	—	—	0.069	—
b	0.22	0.30	0.38	0.0086	0.012	0.015
c	0.13	0.15	0.20	0.0051	0.006	0.0079
D	7.08	7.20	7.34	0.279	0.284	0.289
E	7.40	7.80	8.20	0.291	0.307	0.323
E1	5.00	5.30	5.60	0.197	0.209	0.220
e	—	0.65	—	—	0.0256	—
L	0.56	0.75	0.97	0.022	0.030	0.037
φ	—	4"	8"	—	4"	8"
y	—	—	0.076	—	—	0.003

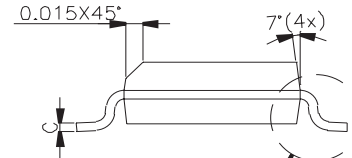
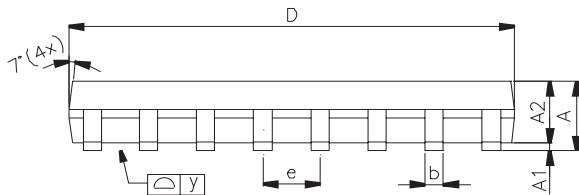
20-pin SSOP

CUSTOMER :		ZYWYN CORPORATION	
APPROVED BY	DATE	TITLE:	
DRAW BY: <i>Monica Chen</i>	09/29/00	20L MEDIUM FINE PITCH STANDARD SMALL OUTLINE PACKAGE DRAWING	
CHECK BY: <i>Lee Chen</i>	12/01/00	DWG. NO.	PO-SSOP-010
APPROVAL: <i>Paul Lee</i>	12/01/00	REV.	0
APPROVAL: <i>Jack Tu</i>	12/01/00	UNIT :	INCH
		SCALE :	12/1
		SHEET :	1 OF 1





DETAIL A



DETAIL A

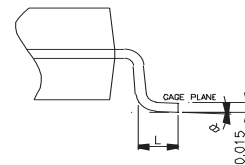
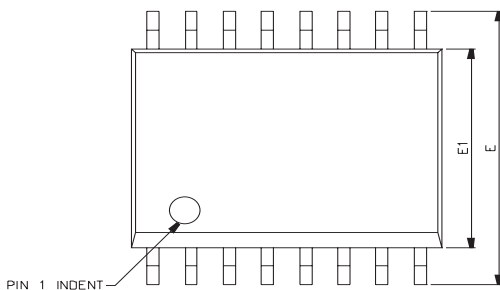
NOTE :

1. CONTROLLING DIMENSION : INCH
2. LEAD FRAME MATERIAL : COPPER 194
3. DIMENSION "D" DOES NOT INCLUDE MOLD FLASH, TIE BAR BURRS AND GATE BURRS. MOLD FLASH, TIE BAR BURRS AND GATE BURRS SHALL NOT EXCEED 0.006"[0.15mm] PER END DIMENSION "E1" DOES NOT INCLUDE INTERLEAD FLASH. INTERLEAD FLASH SHALL NOT EXCEED 0.010"[0.25mm] PER SIDE.
4. DIMENSION "b" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.003"[0.08mm] TOTAL IN EXCESS OF THE "b" DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD TO BE 0.0028"[0.07mm]
5. TOLERANCE : ±0.010"[0.25mm] UNLESS OTHERWISE SPECIFIED.
6. OTHERWISE DIMENSION FOLLOW ACCEPTABLE SPEC.
7. REFERENCE DOCUMENT : JEDEC SPEC MS-012

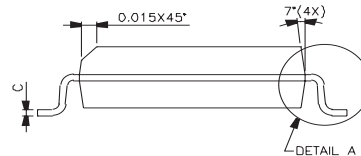
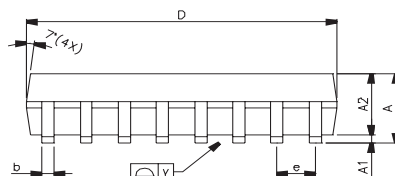
SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.47	1.60	1.73	0.058	0.063	0.068
A1	0.10	—	0.25	0.004	—	0.010
A2	—	1.45	—	—	0.057	—
b	0.33	0.41	0.51	0.013	0.016	0.020
C	0.19	0.20	0.25	0.0075	0.008	0.0098
D	9.80	9.91	10.01	0.386	0.390	0.394
E	5.79	5.99	6.20	0.228	0.236	0.244
E1	3.81	3.91	3.99	0.150	0.154	0.157
e	—	1.27	—	—	0.050	—
L	0.38	0.71	1.27	0.015	0.028	0.050
y	—	—	0.076	—	—	0.003
ø	0"	—	8"	0"	—	8"

16-pin nSOIC

CUSTOMER :		ZYWYN CORPORATION	
APPROVED BY	DATE	TITLE:	
DRAW BY: <i>Monica Chen</i>	11/08/99	16L SMALL OUTLINE PACKAGE DRAWING(0.150")	
CHECK BY: <i>Lee Chen</i>	11/10/99	DWG. NO. PO-SOP-003	REV. 0
APPROVAL: <i>Paul Lee</i>	11/10/99	UNIT :	SCALE : 12/1
APPROVAL: <i>Jack Ju</i>	11/17/99	INCH	SHEET 1 OF 1



DETAIL A



DETAIL A

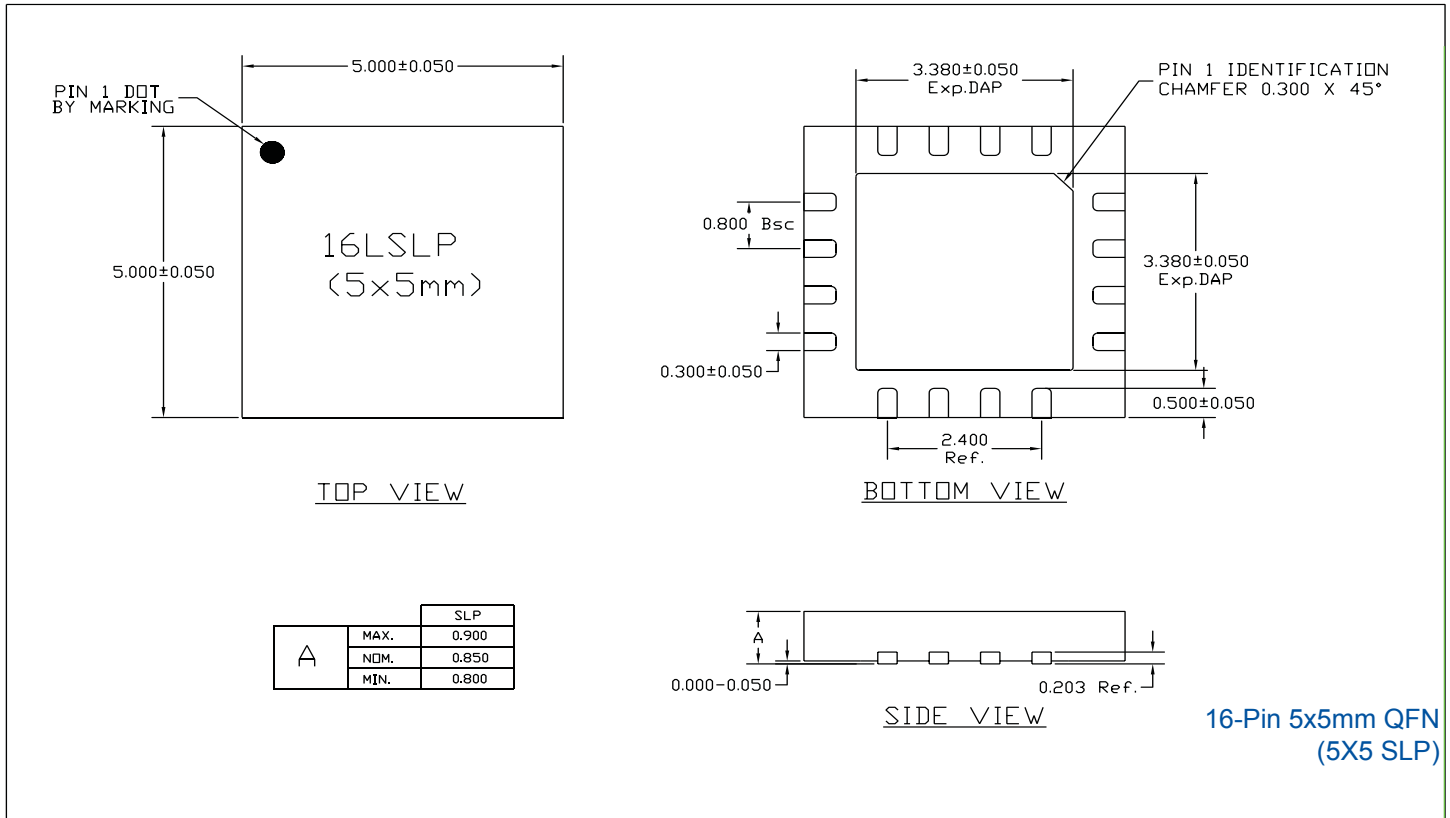
NOTE :

1. CONTROLLING DIMENSION : INCH
2. LEAD FRAME MATERIAL : COPPER 194
3. DIMENSION "D" DOES NOT INCLUDE MOLD FLASH, TIE BAR BURRS AND GATE BURRS. MOLD FLASH, TIE BAR BURRS AND GATE BURRS SHALL NOT EXCEED 0.006"[0.15mm] PER END DIMENSION "E1" DOES NOT INCLUDE INTERLEAD FLASH. INTERLEAD FLASH SHALL NOT EXCEED 0.010"[0.25mm] PER SIDE.
4. DIMENSION "b" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.003"[0.08mm] TOTAL IN EXCESS OF THE "b" DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD TO BE 0.0028"[0.07mm]
5. TOLERANCE : ±0.010"[0.25mm] UNLESS OTHERWISE SPECIFIED.
6. OTHERWISE DIMENSION FOLLOW ACCEPTABLE SPEC.
7. REFERENCE DOCUMENT : JEDEC SPEC MS-013

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	2.36	2.49	2.64	0.093	0.098	0.104
A1	0.10	—	0.30	0.004	—	0.012
A2	—	2.31	—	—	0.091	—
b	0.33	0.41	0.51	0.013	0.016	0.020
C	0.18	0.23	0.28	0.007	0.009	0.011
D	10.08	10.31	10.49	0.397	0.406	0.413
E	10.01	10.31	10.64	0.394	0.406	0.419
E1	7.39	7.49	7.59	0.291	0.295	0.299
e	—	1.27	—	—	0.050	—
L	0.38	0.81	1.27	0.015	0.032	0.050
y	—	—	0.076	—	—	0.003
ø	0"	—	8"	0"	—	8"

16-pin wSOIC

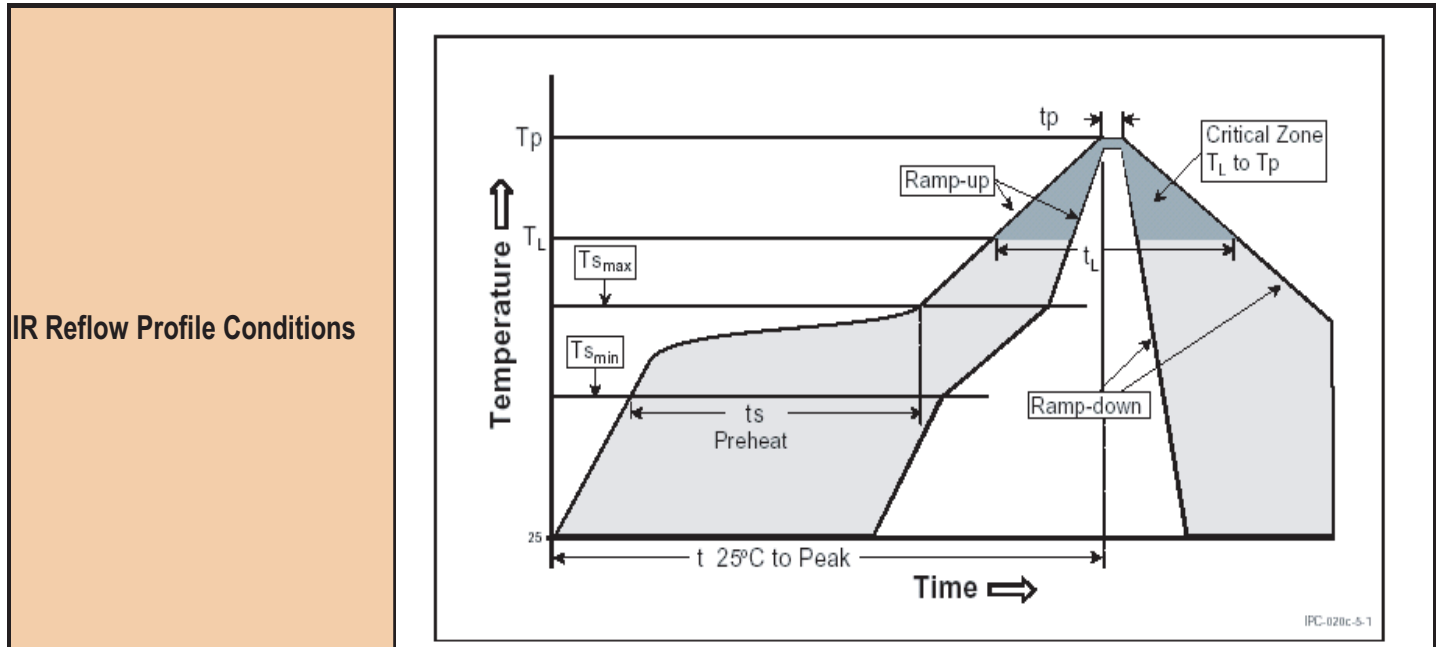
CUSTOMER :		ZYWYN CORPORATION	
APPROVED BY	DATE	TITLE:	
DRAW BY: <i>Monica Chen</i>	10/28/99	16L WIDE BODY SMALL OUTLINE PACKAGE DRAWING	
CHECK BY: <i>Lee Chen</i>	11/01/99	DWG. NO. PO-SOP-004	REV. 0
APPROVAL: <i>Paul Lee</i>	11/02/99	UNIT :	SCALE : 8/1
APPROVAL: <i>Jack Ju</i>	11/02/99	INCH	SHEET 1 OF 1



16-Pin 5x5mm QFN (5X5 SLP)

					TOLERANCES REFER TO SPECIFICATION ABOVE	UNIT: MM SCALE: NTS	DESIGNED: BEN ONG	DATE:	ZYWYN CORPORATION
							APPD: ANDREW TAN APPD: CW CHAI APPD: GC TAN APPD: YC CHOO	DATE:	
REV.	DESCRIPTION	DATE	BY	APPD			DWG. NO: PO-16(SLP)5x5-3.38x3.38	REV.: 00	16L (SLP) 5x5 mm (PACKAGE OUTLINE)

Green Package SMD IR Reflow Profile Information



Profile Feature	JESD Sn-Pb Eutectic Assembly	JESD Pb-free Assembly
Average Ramp-Up Rate (T _{Smax} to T _P)	3°C/seconds max.	3°C/seconds max.
Pre-heat		
- Temperature Min (T _{Smin})	100°C	150°C
- Temperature Max (T _{Smax})	150°C	200°C
- Time (T _{Smin} to t _{Smax})	60~120 seconds	60~180 seconds
Time maintained above:		
- Temperature (T _L)	183°C	217°C
- Time (t _L)	60~150 seconds	60~150 seconds
Peak/Classification Temperature (T _P)	235°C+5/-0°C	255°C+5/-0°C
Time within 5°C of actual Peak Temperature (t _p)	10~30 seconds	20~40 seconds
Ramp-Down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

Zywyn Green Packages are Pb-free and RoHS compliance.

Ordering Information

Part Number	Temperature Range	Package Type	
ZT3220LEEA	-40°C to +85°C	16-pin SSOP	▲
ZT3220LEET	-40°C to +85°C	16-pin WSOIC	▲
ZT3220LEEY	-40°C to +85°C	16-pin TSSOP	▲
ZT3221LEEA	-40°C to +85°C	16-pin SSOP	▲
ZT3221LEEY	-40°C to +85°C	16-pin TSSOP	▲
ZT3222LEEA	-40°C to +85°C	20-pin SSOP	▲
ZT3222LEET	-40°C to +85°C	18-pin WSOIC	▲
ZT3222LEEY	-40°C to +85°C	20-pin TSSOP	▲
ZT3223LEEA	-40°C to +85°C	20-pin SSOP	▲
ZT3223LEEY	-40°C to +85°C	20-pin TSSOP	▲
ZT3232LEEA	-40°C to +85°C	16-pin SSOP	▲
ZT3232LEEN	-40°C to +85°C	16-pin nSOIC	▲
ZT3232LEET	-40°C to +85°C	16-pin WSOIC	▲
ZT3232LEEY	-40°C to +85°C	16-pin TSSOP	▲
ZT3232LEEQ	-40°C to +85°C	16-pin QFN	▲
ZT1385LEEA	-40°C to +85°C	20-pin SSOP	▲
ZT1385LEET	-40°C to +85°C	18-pin WSOIC	▲

Please contact the factory for pricing and availability on Tape-and-Reel options.

TOPSIDE MARK INSTRUCTIONS:

Line 1 ←
Line 2 ←
Line 3 ←

Pin 1 Indicator (mold dimple)

Line 1: Zywyn (logo)
Line 2: Zywyn Part Number "ZT3232LEEY", Space " ", Date Code (Prod Year & Week)
Line 3: Lot #, dot and Country ".T"
Note: Pin # 1 "▲" Indicator Required if no mold dimple

BOTTOMSIDE MARK INSTRUCTIONS:

No backside marking

TOPSIDE MARK INSTRUCTIONS:

Line 1 ←
Line 2 ←
Line 3 ←

Line 1: Zywyn (logo)
Line 2: Zywyn Part Number "ZT3232QT", Country "T"
Line 3: Date Code (Prod Year & Week), Lot # (last 4 characters from the right after the dot, but exclude the dot)
Note: Pin # 1 "▲" Indicator Required if no mold dimple

BOTTOMSIDE MARK INSTRUCTIONS:

No backside marking

Zywyn Corporation

Headquarters and Sales Office

1270 Oakmead Parkway, Suite 201 • Sunnyvale, CA 94085 • Tel: (408) 733-3225 • Fax: (408) 733-3206

Email: sales@zywyn.com • www.zywyn.com

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